ABSTRACT OF THE DISCLOSURE

METHODS OF FABRICATION OF LEAD FRAME-BASED SEMICONDUCTOR DEVICE PACKAGES INCORPORATING AT LEAST ONE LAND GRID ARRAY PACKAGE

Methods of fabrication of lead frame-based semiconductor device packages including at least one land grid array package. At least one semiconductor die is mounted to an interposer substrate, with bond pads of the semiconductor die connected to terminal pads of the interposer substrate. The terminal pads of the interposer substrate may be electrically connected to both a peripheral array pattern of lands and to a central, two-dimensional array pattern of pads, both array patterns located on an opposing side of the interposer substrate from the at least one semiconductor die. The at least one semiconductor die is overmolded with an encapsulant, leaving the opposing side of the interposer substrate free of encapsulant. Lead fingers of a lead frame superimposed on the opposing side of the interposer substrate are bonded directly to the land grid array lands.

[FIG. 4]